

# HMC466LP4 / 466LP4E

v03.1109



MMIC VCO w/ BUFFER AMPLIFIER, 6.1 - 6.72 GHz

### Typical Applications

Low noise MMIC VCO w/Buffer Amplifier for:

- VSAT & Microwave Radio
- CATV & Broadcast Relays
- Test Equipment & Industrial Controls
- Military

#### **Features**

Pout: +4.5 dBm

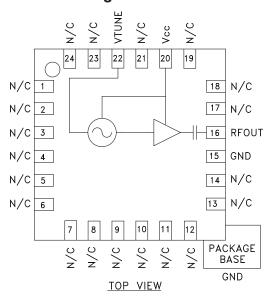
Phase Noise: -101 dBc/Hz @100 KHz

No External Resonator Needed

Single Supply: +3V @ 31 mA

24 Lead 4x4mm QFN Package: 16 mm<sup>2</sup>

### **Functional Diagram**



#### **General Description**

The HMC466LP4 & HMC466LP4E are GaAs InGaP Heterojunction Bipolar Transistor (HBT) MMIC VCOs with integrated resonators, negative resistance devices, varactor diodes, and buffer amplifiers. Covering 6.1 to 6.72 GHz, the VCO's phase noise performance is excellent over temperature, shock, vibration and process due to the oscillator's monolithic structure. Power output is 4.5 dBm typical from a single supply of 3V @31mA. The voltage controlled oscillator is packaged in a low cost leadless QFN 4 x 4 mm surface mount package.

# Electrical Specifications, $T_{\Delta} = +25^{\circ}$ C, Vcc = +3V

| Parameter  | Min.       | Тур.       | Max. | Units      |
|--|------------|------------|------|------------|
| Frequency Range  | 6.1 - 6.72 |            |      | GHz        |
| Power Output   | 1.5        | 4.5        |      | dBm        |
| SSB Phase Noise @ 100 kHz Offset, Vtune= +5V @ RF Output |            | -101       |      | dBc/Hz     |
| Tune Voltage (Vtune)                                     | 0          |            | 10   | V          |
| Supply Current (Icc) (Vcc = +3V)                         |            | 31         |      | mA         |
| Tune Port Leakage Current                                |            |            | 10   | μA         |
| Output Return Loss                                       |            | 7          |      | dB         |
| Harmonics<br>2nd<br>3rd                                  |            | -13<br>-24 |      | dBc<br>dBc |
| Pulling (into a 2.0:1 VSWR)                              |            | 11         |      | MHz pp     |
| Pushing @ Vtune= +5V                                     |            | 30         |      | MHz/V      |
| Frequency Drift Rate                                     |            | 0.8        |      | MHz/°C     |

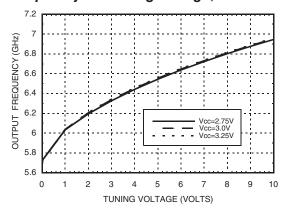


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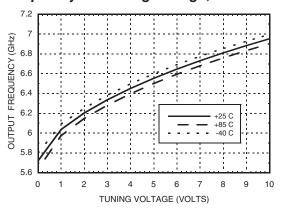


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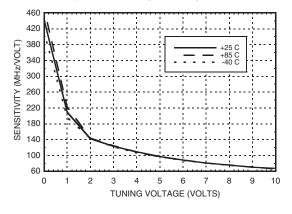
#### Frequency vs. Tuning Voltage, T= 25°C



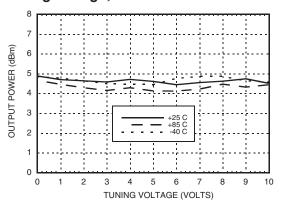
#### Frequency vs. Tuning Voltage, Vcc= +3V



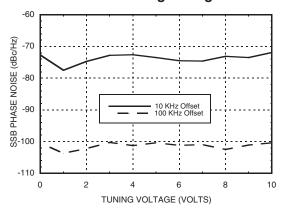
#### Sensitivity vs. Tuning Voltage, Vcc= +3V



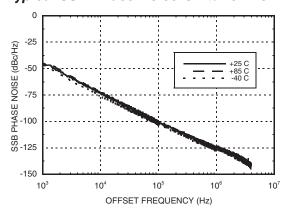
Output Power vs.
Tuning Voltage, Vcc= +3V



#### Phase Noise vs. Tuning Voltage



Typical SSB Phase Noise @ Vtune= +5V



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### **Absolute Maximum Ratings**

| Vcc   | +3.5 Vdc       |  |
|---|----------------|--|
| Vtune   | 0 to +11V      |  |
| Channel Temperature   | 135 °C         |  |
| Continuous Pdiss (T = 85°C)<br>(derate 6.28 mW/°C above 85°C) | 5.65 W         |  |
| Storage Temperature   | -65 to +150 °C |  |
| Operating Temperature   | -40 to +85 °C  |  |

# Typical Supply Current vs. Vcc

| Vcc (V) | Icc (mA) |
|---------|----------|
| 2.75    | 22       |
| 3.0     | 31       |
| 3.25    | 41       |

Note: VCO will operate over full voltage range shown above.



ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

# **Outline Drawing**

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#### NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
   PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOT FOR SUGGESTED LAND PATTERN.

# **Package Information**

| Part Number | Package Body Material                              | Lead Finish   | MSL Rating | Package Marking [3] |
|-------------|--|---------------|------------|---------------------|
| HMC466LP4   | Low Stress Injection Molded Plastic                | Sn/Pb Solder  | MSL1 [1]   | H466<br>XXXX        |
| HMC466LP4E  | RoHS-compliant Low Stress Injection Molded Plastic | 100% matte Sn | MSL1 [2]   | H466<br>XXXX        |

- [1] Max peak reflow temperature of 235  $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260  $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX



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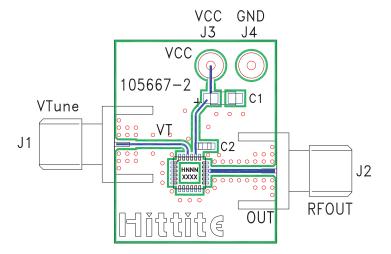


# MMIC VCO w/ BUFFER AMPLIFIER, 6.1 - 6.72 GHz

#### **Pin Descriptions**

| Pin Number                    | Function | Description   | Interface Schematic             |
|-------------------------------|----------|---|---------------------------------|
| 1- 14, 17 - 19,<br>21, 23, 24 | N/C      | No Connection   |                                 |
| 15                            | GND      | This pin must be connected to RF & DC ground. Package bottom has an exposed metal paddle that must be RF & DC grounded. | =<br>O GND                      |
| 16                            | RFOUT    | RF output (AC coupled)  | —                               |
| 20                            | Vec      | Supply Voltage Vcc= 3V  | Vcc O26pF                       |
| 22                            | VTUNE    | Control Voltage Input. Modulation port bandwidth dependent on drive source impedance.                                   | VTUNE 0 1500<br>5.2pF C;= 7.8pF |

#### **Evaluation PCB**



#### List of Materials for Evaluation PCB 105706 [1]

| Item    | Description                    |
|---------|--------------------------------|
| J1 - J2 | PCB Mount SMA RF Connector     |
| J3 - J4 | DC Pin                         |
| C1      | 4.7 μF Tantalum Capacitor      |
| C2      | 10,000 pF Capacitor, 0603 Pkg. |
| U1      | HMC466LP4 / HMC466LP4E VCO     |
| PCB [2] | 105667 Eval Board              |

[1] Reference this number when ordering complete evaluation PCB  $\,$ 

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

# **Mouser Electronics**

**Authorized Distributor** 

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Analog Devices Inc.:

HMC466LP4E 105706-HMC466LP4 HMC466LP4ETR